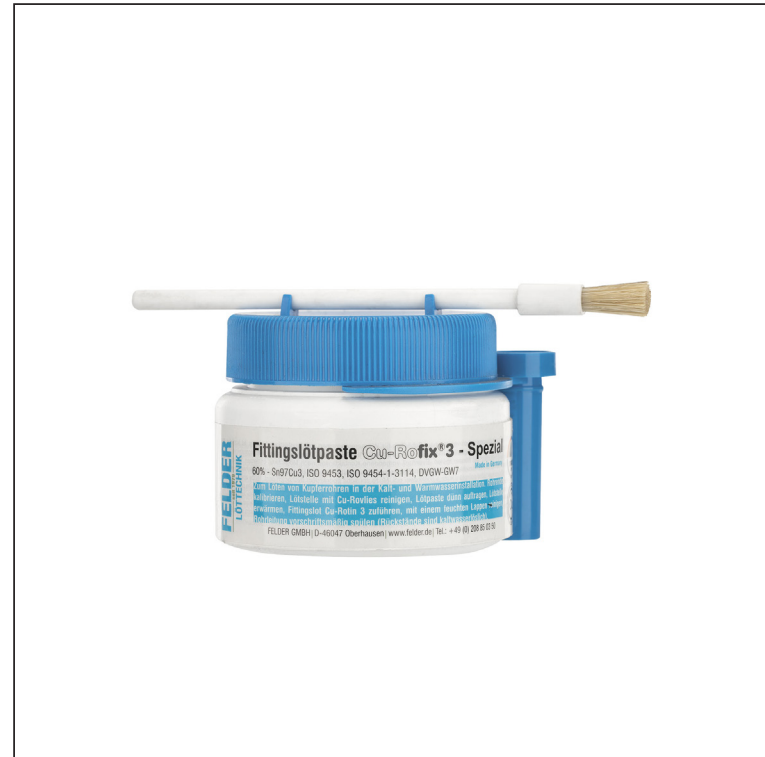


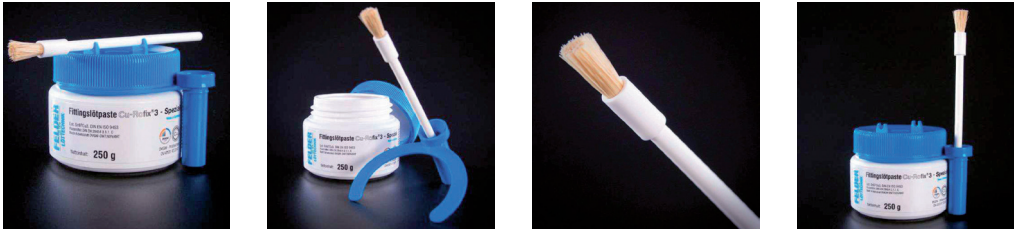
TECHNICAL SHEET

FITTING SOLDER PASTE



SCH-FELD ROFIX 250G



APPLICATION:



Technical parameter	
Application	finished soft solder paste for preliminary and soft soldering copper products
Melting Point	230 – 250 °C
Boiling Point	100 °C
Flash Point	135 °C
Weight	250 g/pcs

INDEX	CHANGE	DATE	SIGNATURE		
MATERIAL BRAND			W.C.	WEIGHT kg	SCALE
SIZE, SEMI-FINISHED PRODUCTS				STN STANDARD	SORTING NUMBER
AUXILIARY EQUIPMENT				NOTE	POSITION NUMBER
ELABORATED BY Ing. Kluska M.					
TESTED BY				OLD DRAWING	DRAWING NUMBER
TECHNOLOGIST			TECHNOLOGIST		
NAME			Fitting solder paste		Number of sheets SCH-FELD ROFIX 250G Sheet 

Created: 03.06.2026 21:06:45

Technical changes reserved